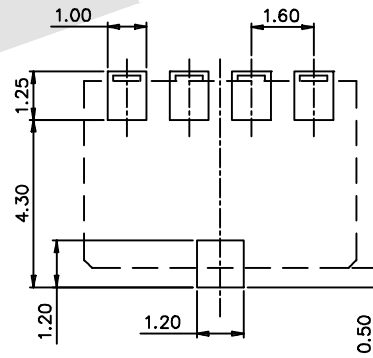
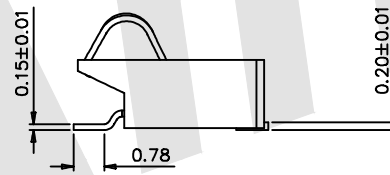
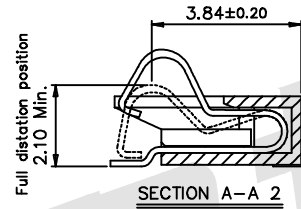
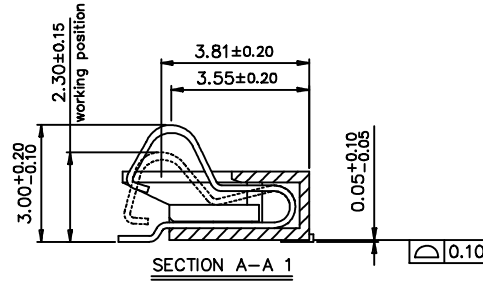
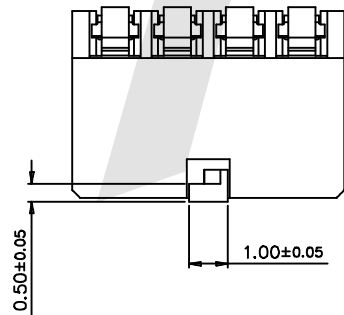
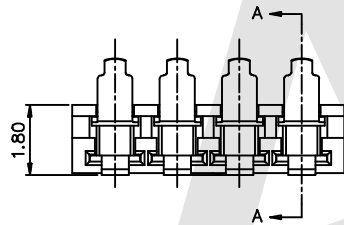
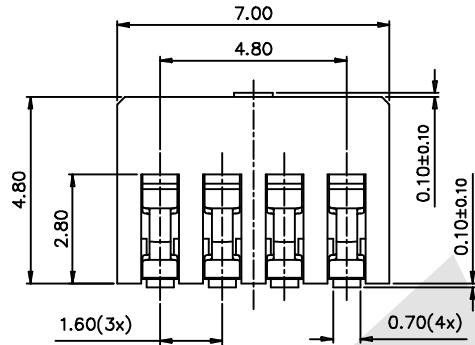


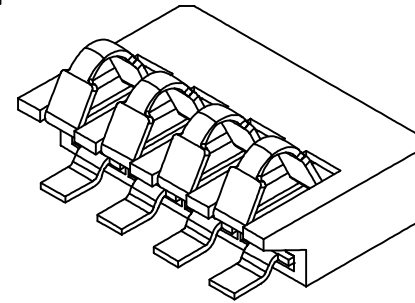
HSF



ROHS



RECOMMENDED PCB LAYOUT
TOLERANCE: ±0.05



NOTES

- MATERIAL:
 - A. PIN: BERYLLIUM COPPER
 - B. INSULATOR: 30% GLASS-FILLED THERMOPLASTIC LCP OR EQUIVALENT UL94V-0, BLACK.
- FINISH: CONTACT: GOLD FLASH (1° MIN.) ALL OVER, 50-100 MICROINCH (1.27-2.54 MICRON) NICKEL UNDERPLATED ALL OVER
SOLDER TAB: 50-100 (1.27-2.54 MICRON) MICROINCH MATTE TIN, 10-100 MICROINCH (1.27-2.54 MICRON) NICK UNDERPLATED
- ELECTRICAL SPECIFICATIONS:
 - VOLTAGE RATING: 250 VAC MIN
 - CURRENT RATING: 2.0 A MIN
 - DIELECTRIC STRENGTH: 1000 VAC FOR 1 MINUTE MIN
 - INSULATION RESISTANCE: 1000 MEG OHM MIN
 - CONTACT RESISTANCE: 30 MILL. OHM MAX
 - OPERATION TEMPERATURE: -55° C TO +125° C
 - PRODUCT WITHSTANDING REFLOW SOLDERING 260° FOR 10S
- MECHANICAL SPECIFICATIONS:
 - 4.1 DURABILITY: 5,000 CYCLES
 - 4.2 NOTMAL FORCE AT MATED POSITION: 60g MIN
 - 4.3 NOTMAL FORCE AT FULL STROKE: 100g MIN
- PARTS TO BE PACKAGED IN ANTI-STATIC TAPE AND REEL FOR AUTOMATIC PLACEMENT.
- THE CAVITY# IS 0.8±0.10mm HIGH WITH 0.10±0.10mm RECESSED FROM SURFACE.

Ordering Code:

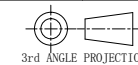
ABT17 - 04 - L - G - X - D

① ② ③ ④ ⑤ ⑥

- ① Series No:
- ② No. of Contacts
04: 04Pin
- ③ Insulator Material:
P: PBT+30%GF
L: LCP
- ④ Pitch
G: 1.6mm Pitch
- ⑤ Contact Plating:
G0: Gold flash
G1: 3u" gold
G2: 5u" gold
G3: 10u" gold
G4: 15u" gold
G5: 30u" gold
- ⑥ Packing:
A: Tray
B: Bag
C: Tube
D: Tape Reel

Unless Otherwise specified tolerance
X. ±0.35 X.XX: ±0.20
X.X: ±0.25 X.XXX: ±0.15

SCALE: As Shown UNIT: mm
DRAW Wu Feng Rong DATE 16/03/2020
CHECK BobYang DATE 16/03/2020



Antenk® ANTENK ELECTRONICS CO., LTD
Http://www.antenk.com
E-mail: sales@antenk.com

TITLE:
1.6 PITCH 4PIN BATTERY CONNECTOR

DRAWING NO: ABT17-04LGXD

PRODUCT NO: ABT17-04LGXD

REV	DESCRIPTION	DATE